

BIOGRAPHY

Pradeep Lall is the MacFarlane Endowed Distinguished Professor and Alumni Professor with the Department of Mechanical Engineering. He is Director of the Auburn University Electronics Packaging Research Institute and the Alabama Node of NextFlex National Manufacturing Institute. He holds a Joint Courtesy Appointment in the Department of Electrical and Computer Engineering. He is a member of the technical council and academic colead of automotive and asset monitoring TWGs of NextFlex Manufacturing Institute. Prior to joining Auburn University, Dr. Lall worked for Motorola, focusing on various aspects of wireless communications products.

He is the author and co-author of over 1000 technical papers, 2-books, and 15 book chapters in the field of electronics reliability, manufacturing, and survivability. He holds three U.S. Patents, Three-Motorola Outstanding Innovation Awards, and Five-Motorola Engineering Awards. His publications have garnered over 13,000 citations, an H-index of 53, and an i10-index of 317. Dr. Lall is ranked in the highest quantile amongst the top 2 percent of Scientific Researchers worldwide, based on data compiled by Stanford University. The ranking system includes scientists in 20 fields and 174 sub-fields. On ranking by field and sub-field, based on career publications, Dr. Lall is ranked in the top 0.3 percent out of 143,311 scientists in the subfield of mechanical engineering & transportation.

Dr. Lall is a fellow of the ASME, a fellow of the IEEE, a fellow of the NextFlex National Manufacturing Institute, and a fellow of the Alabama Academy of Science. He is the recipient of the SMTA Founder's Award in 2024 for exceptional contributions to Electronics Manufacturing, SEMI R&D Achievements Award for landmark contributions to Additive Manufactured Electronics in 2023, ASME Avram Bar-Cohen Memorial Medal in 2022, IEEE Biedenbach Outstanding Engineering Educator Award in 2020, Auburn University Research Advisory Board's Advancement of Research and Scholarship Achievement Award in 2018, IEEE Sustained Outstanding Technical Contributions Award in 2018, NSF's Alex Schwarzkopf Award for Technology Innovation in 2016, Alabama Academy of Science Wright A. Gardner Award in 2016, IEEE Exceptional Technical Achievement Award in 2014, ASME-EPPD Applied Mechanics Award in 2013, SMTA's Member of Technical Distinction Award in 2013, Auburn University's Creative Research and Scholarship Award in 2013, SEC Faculty Achievement Award in 2013, Samuel Ginn College of Engineering Senior Faculty Research Award in 2007 and 2016, and over Fifty Best-Paper Awards at national and international conferences.

Dr. Lall has served in several distinguished roles at the national and international level including serving as a member of the National Academies Committee on Electronic Vehicle Controls, IEEE Electronics Packaging Society Board-of-Governors, Member of the IEEE Reliability Society AdCom, IEEE Electronics Packaging Society Representative on the IEEE-USA Artificial Intelligence Policy Committee, IEEE Reliability Society Representative on the IEEE-USA Government Relations Council for R&D Policy, Chair of Congress Steering Committee for the ASME Congress, Member of the technical committee of the European Simulation Conference EuroSIME, Associate Editor for the IEEE Access Journal, and Associate Editor for the IEEE Transactions on Components and Packaging Technologies. Dr. Lall is the founding faculty advisor for the SMTA student chapter at Auburn University and a member of the editorial advisory board for SMTA Journal. He received the M.S. and Ph.D. degrees in Mechanical Engineering from the University of Maryland and the M.B.A. from Northwestern University.

Pradeep Lall, Ph.D., M.B.A.

*MacFarlane Endowed Distinguished Professor and Alumni Professor, Mechanical Engineering
Joint-Appointment by Courtesy, Electrical and Computer Engineering
Director, Auburn University Electronics Packaging Research Institute
Director, Alabama Node of NextFlex Manufacturing Institute
Academic Co-Lead, SEMI FHE Reliability and Test Standards Task Force*

EDUCATION

University of Maryland	Mechanical Engineering	Ph.D.	1993
Northwestern University	Finance, Strategy	M.B.A.	2002
University of Maryland	Mechanical Engineering	M.S.	1989
Delhi College of Engineering	Mechanical Engineering	B.E.	1988

CURRENT POSITIONS HELD

AUBURN UNIVERSITY

2023 – Present	Alumni Professor
2019 – Present	John and Anne MacFarlane Endowed Distinguished Professor
2024 – Present	Director, Auburn University Electronics Packaging Research Institute
2025 – Present	Director, Alabama Node of NextFlex Manufacturing Institute
2015 – Present	Technical Council, NextFlex Manufacturing Institute
2019 – Present	Board Member, East Alabama Health Foundation
2019 – Present	Board Member, Kellogg Alumni Club of Atlanta
2021 – Present	Academic Co-Lead, Automotive Electronics TWG, NextFlex
2016 – Present	Academic Co-Lead, Asset Monitoring and Situational Awareness TWG, NextFlex
2023 – Present	Academic Co-Lead, SEMI FHE Reliability and Test Standards Task Force

PREVIOUS POSITIONS HELD AUBURN

UNIVERSITY

2008 – 2024	Director, NSF-CAVE3 Electronics Research Center
2017 – 2020	Governing Council, NextFlex Manufacturing Institute
2015 – 2019	John and Anne MacFarlane Endowed Professor
2008 – 2015	Thomas Walter Professor and Director
2006 – 2008	Thomas Walter Professor and Associate Director
2005 – 2006	Thomas Walter Associate Professor and Associate Director
2004 – 2005	Associate Professor and Associate Director
2002 – 2004	Associate Professor

MOTOROLA, INC.

2001 – 2002	Distinguished Member of Technical Staff, Motorola, Inc., Illinois
1999 – 2001	Manager, Component & Interconnect Reliability Laboratory, Motorola, Inc., Illinois
1997 – 1999	Senior Staff Engineer, Motorola, Inc., Illinois
1994 – 1997	Lead Engineer, Motorola, Inc., Florida

UNIVERSITY OF MARYLAND

1992 – 1994	Assistant Director, CALCE Electronic Packaging & Systems Center, University of Maryland, College Park, Maryland
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RESEARCH INTERESTS

Additive-Printed Flexible Electronics, Flexible Hybrid Electronics, Electronics Reliability, Electronics Defects and Quality, Semiconductor Packaging, Electronics Manufacturing, Light Emitting Diodes, MEMS, Wirebonding, Shock and Vibration, Diagnostics, Testing, Prognostics Health Management, Harsh Environment Electronics, Electronics Failure Mechanisms, Modeling and Simulation

SUMMARY

AWARDS

Awards and Honors:	48 Awards
Best-Paper Awards:	66 Awards
Engineering Awards:	5 Awards
Publication Awards:	4 Awards
US Patents:	3 Patents

PUBLICATIONS

Conference Papers:	980 Papers
Journal Papers:	102 Papers
Books:	2 Books
Book Chapters:	15 Chapters

SELECTED NOTABLES:

1. SMTA Founder's Award (2024)
2. SEMI's FLEXI R&D Achievements Award (2023)
3. ASME Avram Bar-Cohen Memorial Medal (2022)
4. IEEE Biedenbach Outstanding Engineering Educator Award (2020)
5. Fellow of the NextFlex National Manufacturing Institute (2019)
6. IEEE Electronic Packaging Society's Outstanding Sustained Technical Contribution Award (2018)
7. NSF-IUCRC Alex Schwarzkopf Prize for Technology Innovation (2016)
8. Samuel-Ginn College of Engineering Senior Faculty Research Award (2016)
9. Wright A. Gardner Award, Alabama Academy of Sciences (2016)
10. IEEE Exceptional Technical Achievement Award (2014)
11. Fellow of Alabama Academy of Sciences (2014)
12. ASME-EPPD Applied Mechanics Award (2013)
13. Member of Technical Distinction Award, Surface Mount Technology Association, SMTA (2013)
14. AU Creative Research and Scholarship Award (2013)
15. Fellow, IEEE (2012)
16. Fellow, ASME (2008)
17. SEC Faculty Achievement Award (2013)
18. Member, NAE Panel, Electronic Vehicle Controls and Unintended Acceleration (2010)
19. Samuel Ginn College of Engineering Senior Faculty Research Award, Auburn University (2007).
20. Thomas Walter Associate Professor, Samuel Ginn College of Engineering, Auburn University (2005)
21. 6- σ (Six-Sigma) Black Belt in Statistics, Motorola, Inc. (2001)

JOURNAL REVIEW & REVIEW PANELS

1. Journal Editorships: 9-Appts
2. Associate Editor, IEEE Transactions on Components Packaging and Manufacturing Technologies (TCPT)
3. Associate Editor, IEEE Access Journal
4. Reviewer for Major Journals in IEEE and ASME including ADVP, TCPT, TEPM, JEP
5. Expert Panels: 18 Panels

PROFESSIONAL SOCIETIES

1. Conference & Session Chairmanships: 184-Appts
2. General Chair, ASME InterPACK 2024
3. Conference General Vice-Chair, ASME InterPACK 2023
4. Track Co-Chair, Flexible Electronics, ASME InterPACK 2023
5. Conference Sponsorship Chair, ASME InterPACK 2022
6. IEEE Electronic Packaging Society Board of Governors, 2019-2024
7. Member, IEEE Reliability Society AdCom, 2010 – 2019.
8. IEEE Reliability Society Fellows Selection Committee, 2013–present.
9. General Chair, IEEE PHM 2015
10. Member, IEEE USA Government Relations Council, R & D Committee, 2013 – present.
11. Chair, Congress Steering Committee Senate (2013)
12. Congress Steering Committee Chair (2012-13)
13. General Chair, ASME Congress (2010)
14. Technical Program Chair, ASME Congress (2009)
15. Technical Program Vice-Chair, ASME Congress (2008)
16. Chair, SEM, Electronic Packaging TD (2008)
17. SMTA Technical Committee (2010)
18. Chair, IEEE ECTC Modeling & Simulation (2010)

CENTER DIRECTOR EXPERIENCE (20+ Yrs)

2008-Present: Director, NSF-CAVE3
 2004-2008: Associate Director, NSF-CAVE3
 1992-1994: Assistant Director, CALCE Center, UMD

CHAired-PROFESSORSHIPS (18+ Yrs)

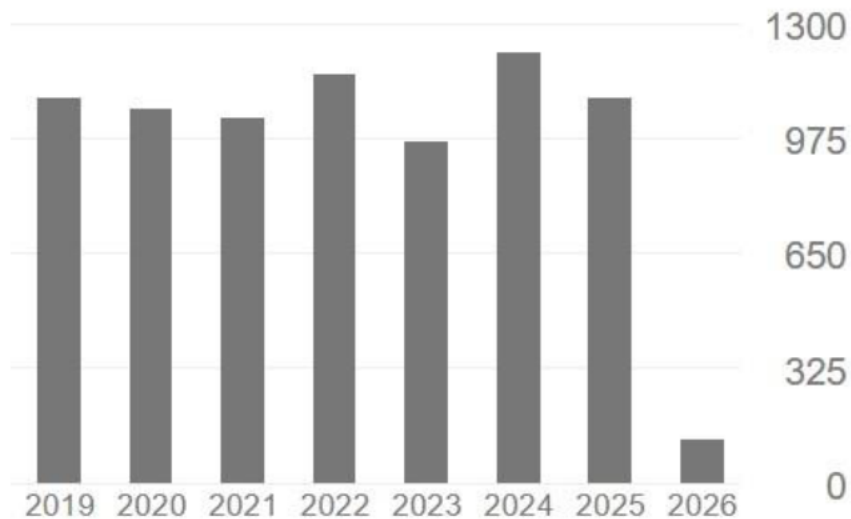
2023 – Present	Auburn University Alumni Professor
2019 – Present	MacFarlane Distinguished Professor
2015 – 2019	MacFarlane Endowed Professor
2005 – 2015	Thomas Walter Professor

CITATION INDICES

Cited by

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3. AWARDS & HONORS

1. SMTA Founder's Award (2024)
2. Alumni Professorship, Auburn Alumni Association (2023)
3. FLEXI R&D Achievements Award, For Landmark Contributions in Developing Additive Manufacturing Processes and Reliability Testing for Additive Printed Flexible Electronics, SEMI FlexTech (2023)
4. Avram Bar-Cohen Memorial Medal, American Society of Mechanical Engineers, (2022)
5. IEEE Biedenbach Outstanding Engineering Educator Award (2020)
6. Professional Member of IEEE-Eta Kappa Nu (IEEE-HKN) International Honor Society of IEEE (2019)
7. John and Anne MacFarlane Endowed Distinguished Professor (2019)
8. Fellow of the NextFlex National Manufacturing Institute on Flexible Electronics (2019)
9. IEEE Electronic Packaging Society Board-of-Governors, Elected Member-at-Large, (2018)
10. Auburn University Research Advisory Board's Advancement of Research and Scholarship Achievement Award (2018).
11. IEEE Electronic Packaging Society's Outstanding Sustained Technical Contribution Award (2018)
12. NSF-IUCRC Alex Schwarzkopf Prize for Technology Innovation (2016)
13. Samuel-Ginn College of Engineering Senior Faculty Research Award (2016)
14. Wright A. Gardner Award, Alabama Academy of Sciences (2016)
15. John and Anne MacFarlane Endowed Professor (2015)
16. IEEE Exceptional Technical Achievement Award, IEEE CPMT Society (2014)
17. Fellow of the Alabama Academy of Sciences (2014)
18. ASME EPPD Applied Mechanics Award, American Society of Mechanical Engineers, (2013)
19. Recipient of Member of Technical Distinction Award, Surface Mount Technology Association, SMTA (2013).
20. Creative Research and Scholarship Award, Auburn University (2013)
21. SEC Faculty Achievement Award (2013)
22. Fellow of IEEE (2012)
23. Member, National Academies Committee, Electronic Vehicle Controls and Unintended Acceleration (2010) 24. Joint Appointment, Department of Finance, Auburn University (2009)
25. Fellow of the ASME, (2008).
26. Samuel Ginn College of Engineering Senior Faculty Research Award, Auburn University (2007).
27. Thomas Walter Professor, Samuel Ginn College of Engineering, Auburn University (2006)
28. Thomas Walter Associate Professor, Samuel Ginn College of Engineering, Auburn University (2005)
29. 6- σ (Six-Sigma) Black Belt in Statistics, Motorola, Inc. (2001)
30. Beta Gamma Sigma Honorary Society. (2002)
31. Jane Robertson Memorial Award Scholar, Northwestern University, (2000)
32. iDen EAGLE Stock Award, Award for Spearheading Successful Implementation of 0.5mm Pitch Chip-Scale Packaging Technology in the iDen EAGLE Pocket Phone, February 1998.
33. Silver Quill Award, Reliability Study of the Laminate Based Flip-Chip Chip-Scale Package, 2nd 1998 IEMT/IMC Symposium, April 15, 1998.
34. Outstanding Innovation Award for 6 Patent Disclosures, 1997
35. Silver Quill Award, Reliability Characterization of the SLICC Package, Pradeep Lall, Glenn Gold, Barry Miles, Kingshuk Banerji, Pat Thompson, Corey Koehler, Indira Adhihetty, Electronics Components and Technology Conference (ECTC), Orlando, Florida, May 28-31, 1996.
36. Outstanding Innovation Award for 7 Patent Disclosures, 1996
37. Outstanding Innovation Award for 9 Patent Disclosures, 1995
38. President of International Society for Hybrid Microelectronics, Student Chapter at University of Maryland.(07/91-5/93)
39. Vice-President of the International Society for Hybrid Microelectronics, Student Chapter at the University of Maryland. (07/90-06/91)
40. Ranked 2nd of 120 students in B.S., Mechanical Engineering, 1988.
41. Merit-Certificate for excellence in investigations on "Design and Analysis of Cooling Towers", B.S., Mechanical Engineering, 1988.
42. Merit-Prize for Standing 1st in "Fluid Systems", B.E., Mechanical Engineering, VI Semester, August 1987.

43. Merit Certificate for Ranking 2nd in 120 students (2nd year B.E.) 1986.
44. Merit-Prize for Standing 1st in "Engineering Mechanics", B.E., Mechanical Engineering, III Semester, March 1986.
45. Merit-Certificate for Ranking 2nd in 120 students (1st year B.E.), 1985.
46. Merit-Prize for - Standing 1st in "Electrical Technology", B.E., Mechanical Engineering, III Semester, March 1986.
47. Merit-Prize for - Standing 1st in "Engineering Materials", B.E., Mechanical Engineering, II Semester, June 1985.
48. Marker Cup for excellence in "Physics", 1983. Gold Medal and Certificate-of-Excellence for meritorious performance in school. (1972-1984).

Best Paper Awards

1. ITherm 2025 Best Poster Runner-Up Award, Mechanics and Reliability Track, Thermal Conductivity Evolution of Non-PFAS Automotive Packaging Materials under High Temperature and Humidity Exposure, Zhang, Y., Lall, P., Harris, D., In Proceedings of the Twenty-Fourth InterSociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm 2025), Dallas, TX, pp. 1131-1139, May 27-30, 2025.
2. ITherm 2025 Best Poster Runner-Up Award, Mechanics and Reliability Track, Humidity and High Temperature Effects on Non-PFAS Thermal Interface and Underfill Materials, Choudhury, P., Pandurangan, A., Lall, P., In Proceedings of the Twenty-Fourth InterSociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm 2025), Dallas, TX, pp. 1123-1130, May 27-30, 2025.
3. 1st Place Nasser Grayeli Best Poster Award: Impact of Thermal Cycling on the Reliability of In-Mold Direct Write Additively Printed Integrators and Active Lowpass Filter, Musa, F., Lall, P., Miller, S., ASME InterPACK, San Jose, CA, Oct 8-10, 2024.
4. 3rd Place Nasser Grayeli Best Poster Award for: "Performance of Oscillator Circuit in Additive In-Mold Electronics for Automotive Applications, Harsha, A., Lall, P., Kulkarni, S., Miller, S., ASME InterPACK, San Jose, CA, Oct 8-10, 2024.
5. ITherm 2024 Best Paper Runner-Up Award, Lall, P., Soni, V., Miller, S., Development and Performance Evaluation of Additively Printed In-Mold Electronic Sensors, , Emerging Technologies and Fundamentals Track, ITherm Conference, Denver, CO, May 28-31, 2024.
6. ITherm 2024 Best Paper Runner-Up Award, Lall, P., Mehta, V., Suhling, J., Locker, D., Investigation of the Effects of Sustained High-Temperature on Reliability of Lead-Free Solder Joint Assemblies in Vibration, Mechanics and Reliability Track, ITherm Conference, Denver, CO, May 28-31, 2024.
7. ITherm 2024 Best Poster Award, Pandurangan, A., Lall, P., Predictive Damage Modeling of Potted Assemblies under High-G Shock Loads, Mechanics and Reliability Track, ITherm Conference, Denver, CO, May 28-31, 2024.
8. ITherm 2024 Best Poster Runner-Up Award, Karakitie, D., Lall, P., Repairability of Additively Printed Circuits Using Sustainable Aqueous-Based Silver Nanoparticle Ink on Polyimide Substrates, Emerging Technologies and Fundamentals Track, ITherm Conference, Denver, CO, May 28-31, 2024.
9. ITherm 2024 Best Poster Runner-Up Award, Bimali, S., Lall, P., Advancing Sustainability in Printed Electronics: Low-Temperature Interconnects and Water-Based Ink Performance, Emerging Technologies and Fundamentals Track, ITherm Conference, Denver, CO, May 28-31, 2024.
10. ITherm 2024 Best Poster Runner-Up Award, Mehta, V., Lall, P., Investigation of the Effects of Sustained High Temperature on the Reliability of Lead-Free Solder Joint Assemblies in Vibration, Mechanics and Reliability Track, ITherm Conference, Denver, CO, May 28-31, 2024.
11. Nasser Grayeli Best Poster Award, Soni, V., Lall, P., Narangaparambil, J., Miller, S., Evaluation of Thermoformability on Gravure-Offset Printed In-Mold Electronic Circuits on Different Substrates, Proceedings of the ASME InterPACK, Based on Paper IPACK2023-112060, pp. 1-11, San Diego Mission Valley, CA, Oct 24-26, 2023.
12. Best-of-Proceedings Honorable Mention: Study of the FCBGGA Package Interfaces Reliability Under Monotonic and Fatigue Loads after Sustained High Temperature, Lall, P., Pandurangan, A., Choudhury, P., Kasturi, M., Proceedings of the SMTA International, Minneapolis, MN, USA, pp. 38-48, Oct 9 -12, 2023.
13. Intel Outstanding Paper Award, Lall, P., Soni, V., and Miller S., Additively Printed Flexible Charging Circuits and Effect on Evolution of Line Resistance and Charging Current in Charging Thin Flexible Batteries, IPACK2022-97450, in Proceedings of the ASME InterPACK 2022, Garden Grove, CA, pp. 1-8, October 25-27, 2022.

14. Intel Best Paper Award – Honorable Mention Award: Lall, P., Narangaparambil, J., and Hill, C., Influence of Cure-Reflow Profile and High-Temperature Operation of Additively Printed Conductive Circuits on Performance and Reliability, IPACK2022-97457, in Proceedings of the ASME InterPACK 2022, Garden Grove, CA, pp. 1-11, October 25-27, 2022.
15. Nasser-Grayeli Best Poster Award, Estimation of State of Health Degradation of Thin Flexible Li-Ion Batteries Subjected to Accelerated Life Cycling with Randomized Levels of Charge-Discharge and Varying C-Rates, Soni, V., Lall, P., IPACK2022-99241, ASME InterPACK 2022, Garden Grove, CA, October 25-27, 2022.
16. Nasser-Grayeli Best Poster Award, Plastic Work Evolution and High Strain Rate Properties at Extreme Temperatures for SAC-Q Solder Alloy With Extended Durations of High Temperature Aging, Mehta, V., Lall, P., IPACK2022-99233, ASME InterPACK 2022, Garden Grove, CA, October 25-27, 2022.
17. Outstanding Poster Award – Mechanics and Reliability Track: Lall, P., J. Narangaparambil, and S. Miller, Influence of Component Interconnect with Printed Copper Circuits on Realized Mechanical and Electrical Characteristics in FHE Applications, in Proceedings of the InterSociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 950-960, May 31-June 3, 2022.
18. Student Research Best-Paper Award: “Reliability and IMC Layer Evolution of Homogenous Lead-Free Solder Joints During Thermal Cycling” by Mohamed El Amine Belhadi, Xin Wei, Palash Vyas, Rong Zhao, Sa’d Hamasha, Haneen Ali, Jeff Suhling, Pradeep Lall, Barton C. Prorok, Proceedings of the IPC APEX EXPO, pp. 1-14, San Diego, CA, Jan 25-27, 2022
19. Honorable Mention: “Reliability SoH Degradation and Life Prediction of Thin Flexible Batteries Under Flex-to-Install Dynamic Folding, Dynamic Twisting and Battery Lamination” by Pradeep Lall, Ved Soni, Jinesh Narangaparambil, Hyesoo Jang, Scott Miller, Proceedings of the IPC APEX EXPO, pp. 1-14, San Diego, CA, Jan 25-27, 2022
20. Nasser Grayeli Outstanding Poster Award: Effect of Fold Diameter on State-of-Health Degradation of Li-ion Batteries Subjected to U-Flex-to-Install and Dynamic U-Fold Testing, P. Lall, V. Soni, S. Miller, pp 1-8, ASME InterPACK International Technical Conference and Exhibition, Oct 26-28, 2021.
21. Intel Student Best Paper Award: Mechanical Behavior and Reliability of SAC+Bi Lead Free Solders with Various Levels of Bismuth, K. R. Hassan, J. Wu, M. S. Alam, J. C. Suhling and P. Lall, IEEE 71st Electronic Components and Technology Conference (ECTC), pp. 937-945, 2021.
22. Prof. Avram Bar-Cohen Best Paper Award: Process Recipes for Additively Printed Copper-Ink Flexible Circuits using Direct Write Methods, Lall, P., J. Narangaparambil, K. Schulze, and C. Hill, in Proceedings of the IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 1061-1072, June 1-4, 2021.
23. Prof. Avram Bar-Cohen Best Paper Award: Lall, P., T. Thomas, and K. Blecker, Prognostic and RUL Estimations of SAC105, SAC305 and SnPb Solders under Different Drop and Shock Loads using Long ShortTerm Memory (LSTM) Deep Learning Technique, in Proceedings of the IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 644-658, June 1-4, 2021.
24. Best Poster Award: Effect of Thermal Aging on the Interface Fracture Toughness of PCB-UF Interface, P. Lall, P. Choudhury, and J. Williamson, in Proceedings of the IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 601-609, June 1-4, 2021.
25. Outstanding Paper of Conference Award, Lall, P., K. Goyal, and S. Miller, Process-Consistency in Additive Printed Multilayer Substrates With Offset-Vias Using Aerosol Jet Technology, in Proceedings of the ASME 2020 International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems, ASME INTERPACK, Paper IPACK2020-2680, pp. 1-11, October 27-29, 2020.
26. Outstanding Paper of Conference Award, Lall, P., H. Jang, C. Hill, and L. Creel, Reliability of Flexible Wearable Band With Printed Sensors for Vital Sign Acquisition, in Proceedings of the ASME International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems, ASME INTERPACK, Paper IPACK2020-2644, pp. 1-8, October 27-29, 2020.
27. Outstanding Paper of Conference Award, Mechanics Track: Lall, P., T. Thomas, and K. Blecker, RUL estimations of SAC305 solder PCBs under different conditions of temperature and vibration loads, Proceedings of the 19th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 1340-1349, July 21-23, 2020.
28. Best Overall Poster Award: Mondal, D., A. Fahim, J. Suhling, P. Lall, Modeling Deformation Behavior of Multiple Grained SAC305 Solder Joints, Proceedings of the 19th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 1221-1229, July 21-23, 2020.
29. Outstanding Poster Award, Emerging Technologies & Fundamentals: Lall, P., V. Soni, and S. Miller, Effect of Dynamic Folding with Varying Fold Orientations and C-rates on Flexible Power Source Capacity Degradation,

- Proceedings of the 19th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, pp. 854-860, July 21-23, 2020.
30. Best-of-Conference Paper Award: Lall, P. Yadav, V., Locker, D., Sustained High-Temperature Vibration Reliability of Thermally Aged Lead-Free Assemblies in Automotive Environments, Proceedings of the SMTA Pan Pacific Conference, pp-1-18, Big Island, HI, February 10-13, 2020.
 31. Outstanding Paper Award of Conference: Lall, P., Narangaparambil, J., Leever, B., Miller, S., Flexure and Twist Test Reliability Assurance Of Flexible Electronics, ASME InterPACK, IPACK2019-6579, Anaheim, CA, Oct 7-9, 2019.
 32. Outstanding Poster Award: Lall, P., V. Soni, A. Abrol, B. Leever, and S. Miller, Effect of Shallow Charging on Flexible Power Source Capacity Subjected to Varying Charge Protocols and C-Rates, in Proceedings of the IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, Las Vegas, NV, pp. 198-203, May 28-31, 2019.
 33. Best Poster Award: Wu, J., S. Ahmed, J. Suhling, and P. Lall, Investigation of Aging Induced Microstructural Changes in Doped SAC+X Solders, in Proceedings of the IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, Las Vegas, NV, pp. 405-415, May 28-31, 2019.
 34. Best Overall Poster Award: Su, S., J. Minghong, X. Wei, F. Akkara, S. Hamasha, J. Suhling, and P. Lall, Effect of Surface Finish on the Fatigue Behavior of Bi-based Solder Joints, in Proceedings of the IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, Las Vegas, NV, pp. 11551159, May 28-31, 2019.
 35. Outstanding Paper Award, Oral Session, Mechanics and Reliability Track, P. Lall, Y. Luo and L. Nguyen, A Novel Numerical Multiphysics Framework for the Modeling of Cu-Al Wire Bond Corrosion under HAST Conditions, ITherm, San Diego, CA, US, pp. 1177-1184, May 29-June 1, 2018.
 36. Outstanding Paper-Award, Poster-Session, Mechanics and Reliability Track, Abrol, A., Lall, P., Flexible Power Source Survivability Assurance Under Bending Loads and Operating Temperatures Representative of Stresses of Daily Motion, Proceedings of the ITherm Conference, San Diego, CA, US, pp. 1027-1035, May 29-June 1, 2018.
 37. Best Paper Award, Poster-Session, Mechanics and Reliability Track, A. Fahim, S. Ahmed, J. Suhling and P. Lall, Mechanical Characterization of Intermetallic Compounds in SAC Solder Joints at Elevated Temperatures, Proceedings of the ITherm Conference, San Diego, CA, US, pp. 1081- 1091, May 29-June 1, 2018.
 38. Best Poster-Award, Zhang, H., Lall, P., Color Shift Analysis and Modeling of High Power Warm White pcLED under High Temperature and High Humidity Environment, Mechanics and Reliability Track, Proceedings of the ITherm Conference, Orlando, FL, May 30-June 2, 2017.
 39. Outstanding Poster-Award, Yadav, V., Lall, P., High Strain Rate Mechanical Behavior of SAC-Q Solder, Mechanics and Reliability Track, Proceedings of the ITherm Conference, Orlando, FL, May 30-June 2, 2017.
 40. 2015 Best Paper -- IEEE Transactions on Components, Packaging and Manufacturing Technology in the Electronics Manufacturing category: Lall, P., Patel, K., Narayan, K., Model for Inverse Determination of Process and Material Parameters for Control of Package-on-Package Warpage, IEEE Transactions on Components, Packaging and Manufacturing Technology, Volume 5, No. 9., pp. 1358 – 1375, Sept 2015.
 41. 2014-2015 ASME Journal of Electronic Packaging Best-Paper Award (2015); for paper: Lall, P., Lowe, R., Comparison of Prognostic Health Management Algorithms for Assessment of Electronic Reliability Under Vibration, ASME Journal of Electronic Packaging, Volume 136, No. 4, doi:10.1115/1.4028163, pp. 041013-1to 041013-8, December 2014.
 42. Best Poster-Paper Award: Lall, P., Deshpande, S., Nguyen, L., Fuming Acid Based Decapsulation Process for Copper-Aluminum Wirebond System Molded with Different EMC's, Paper IPACKICNMM2015-48638; Session 14-2-1, ASME International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK), San Francisco, CA, pp. 1-13, July 6-9, 2015
 43. Outstanding Poster-Paper Award: Ahmed, S., M. Basit, J. C. Suhling, P. Lall, Characterization of Doped SAC Solder Materials and Determination of Anand Parameters, Paper IPACKICNMM2015-48624, 14-2-2, ASME International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK), San Francisco, CA, pp. 1-14, July 6-9, 2015
 44. Best-of-Conference Oral Session Paper: Hasnine, M., Suhling, J., Prorok, B., Bozack, M., Lall, P., Exploration of Aging Induced Evolution of Solder Joints Using Nanoindentation and Microdiffraction, Electronic Components and Technology Conference, 64th ECTC, pp. 379-394, Orlando, FL, May 27-30, 2014, Award Presented at the 65th ECTC, 2015.
 45. Best Poster-Paper Award: Lall, P., Deshpande, S., Nguyen, L., Murtuza, M., Damage Mechanisms in CopperAluminum Wirebond Under High Temperature Operation, 14th IEEE ITherm Conference, pp. 1171-1178, Orlando, FL, May 27-30, 2014.

46. Best Poster-Paper Award: Lall, P., Harsha, M., Suhling, J., Goebel, K., Damage Pre-Cursors Based Prognostication of Accrued Damage and Assessment of Operational Readiness of Lead-free Electronics, Proceedings of the ASME 2013 International Technical Conference & Exposition on Packaging and Integration of Electronic and Photonic Microsystems, InterPACK2013-73251, pp. 1-17, Burlingame, CA, 2013.
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1. Algorithm To Prevent CPU Overflow Condition, Pradeep Lall, Scott Potter, Engineering Award, 1997.
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3. Method for Solder Joint Geometry Generation, Pradeep Lall, Kingshuk Banerji, Engineering Award, 1999.
4. Method for Generating Map-meshable Areas and Volumes, Pradeep Lall, Kingshuk Banerji, Engineering Award, 1999.
5. Method For Optimizing Electronic Component Solder Joint Geometry, Pradeep Lall, Kingshuk Banerji, Engineering Award, 1999.

U.S. Patents

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2. Surface Mountable Flexible Interconnect, Lall, P., US Patent No. 5,928,001, 1999 (with Gillette, J., Potter; S.)
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4. SCHOLARLY CONTRIBUTIONS 4.A Research and Creative Work

Books and Book Chapters

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916. Drop-Impact Reliability of Chip-Scale Packages in Handheld Products, Tian, G., Liu, Y., Lall, P., Johnson, W., Suhling, J., Proceedings of the ASME International Mechanical Engineering Congress and RD & D Exposition, Washington, D.C., Paper No. IMECE2003-42075, pp. 1-9, November 15-21, 2003.
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960. Practical Approaches to Microelectronic Packaging Reliability Prediction Modeling, Lall, P., Barker, D.B., Dasgupta, A., Pecht, M., Proceedings of International Society of Hybrid Microelectronics, pp. 126-130, Baltimore, MD, Oct. 17-19 1989.
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962. Drop Reliability of Printed Circuit Board Assemblies in Portable Communication Products, Pradeep Lall, Wei Hao, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
963. An Integrated Simulation Tool for Reliability Evaluation on System Level, Charlie Zhai and Pradeep Lall, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
964. A Meshfree Approach for Numerical Simulation of Portable Electronic Products, Wei Hao, Pradeep Lall, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
965. Dynamic-Design-Analysis; An Approach to Printed Circuit Board Design, Material Utilization, and Costing, Gordon Thompson, Hank Liebman, Nitin Desai, Rob Mulligan, John Holley, Jim Zollo, Ilya Lisak, Pradeep Lall, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
966. Thermal Dynamic Resistance Testing for Qualification of Printed Circuit Boards, Gordon Thompson, Hank Liebman, Nitin Desai, John Holley, Pradeep Lall, Jim Zollo, Ilya Lisak, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
967. Improved Methodology for Thermal Mechanical Analysis Testing, Rob Mulligan, Nitin Desai, John Holley, Gordon Thompson, Hank Liebman, Jim Zollo, Ilya Lisak, Pradeep Lall, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
968. Value Assessment Tools and the M-Gate Process, Scott Potter, Kingshuk Banerji, Jim Wang, Pradeep Lall, CL Wong, James How, Proceedings of the HERMES Symposium, Ft. Lauderdale, FL, October 9-13, 2000
969. A Mesh-Free Approach for Numerical Simulation of Portable Electronic Products, Pradeep Lall, Wei Hao, Proceedings of the Simulation & Modeling Symposium, Phoenix, AZ, June 20-22, 2000
970. Development of Simulation Tools for Reliability Prediction of Board Assemblies, Pradeep Lall, Celestino Corral, Proceedings of the Software Simulation and Modeling Symposium, Ft. Lauderdale, June 22-24, 1999.
971. Modeling Reliability Of Plated-Thru Holes In High Tg Multi-Layer Laminates, Pradeep Lall, Nitin Desai, Ilya Lisak, Gordon Thompson, Hank Liebman, HERMES Symposium, Austin, TX, Sept. 20-24, 1999; Proceedings of the Software Simulation and Modeling Symposium, Ft. Lauderdale, June 22-24, 1999.
972. Field-Failure Validation of Board Assembly Thermal Fatigue Reliability Predictions, Pradeep Lall, Hank Liebman, Proceedings of the HERMES Symposium, Austin, TX, Sept. 20-24, 1999.
973. Transient Dynamic Behavior of Digital-Cellular Phone during Drop, Pradeep Lall, Gene Stout, Proceedings of the HERMES Symposium, Austin, TX, Sept. 20-24, 1999.
974. Assembly-level Reliability Characterization of the μ BGA, μ STAR, and 0.5mm Pitch FP-BGA Chip-Scale Packages for the EAGLE Pocket Phone, Pradeep Lall, Kingshuk Banerji, Proceedings of the 1998 Motorola Winter AMT Symposium, January 17-21, 1998
975. Reliability Characterization of the μ BGA Package, Pradeep Lall, Edwin Bradley, Kingshuk Banerji, Proceedings of the 1997 Motorola Summer AMT Symposium, Schaumburg, July 23-24, 1997
976. Reliability Forecasting System-A Software Tool-Set for Reducing Product Development Cycle Time, Pradeep Lall, Kingshuk Banerji, Proceedings of the 1997 Motorola Summer AMT Symposium, Schaumburg, July 23-24, 1997; Modeling & Simulation Symposium, Chicago, July 4-5, 1997
977. Solder Joint Design for Optimum Process and Reliability, Pradeep Lall, Kingshuk Banerji, Proceedings of the 1996 Motorola Summer AMT Symposium, Schaumburg, IL July 24 & 25, 1996, pp. 311-323
978. Approval of an Immersion Nickel Gold Finish for the Eurotraveller Portable Radio, Brian Lee, Roger Callanan, Edwin Bradley, Joe Gillette, Pradeep Lall, Kingshuk Banerji, Proceedings of the 1996 Motorola Summer AMT Symposium, Schaumburg, IL July 24 & 25, 1996, pp.425-432
979. Development of a System Model for Solder Joint Reliability, Pradeep Lall, Kingshuk Banerji, Proceedings of the 1996 Motorola Winter AMT Symposium, Phoenix, Arizona, January 15-19, 1996, pp.753-765
980. Soldering Process Characterization to Evaluate Air versus Nitrogen Reflow, Edwin Bradley, Jesse Galloway, Pradeep Lall, Kingshuk Banerji, Frank Alves, Vahid Goudarzi, Lamberto Roscioli, Proceedings of the 1996 Motorola Winter AMT Symposium, Phoenix, Arizona, January 15-19, 1996

M.S Thesis

Wire and Wire Bond Failures in Microelectronic Packages, Pradeep Lall, Thesis (M.S.),-University of Maryland at College Park, 1989

Ph.D. Dissertation

Influence of Temperature on Microelectronic Device Failures, Pradeep Lall, Dissertation (Ph. D.),-University of Maryland at College Park, 1993.

4.B Teaching

4.B.1 Teaching Interests

1. Continuum Mechanics and Tensor Analysis
2. Finite Element Methods
3. Principles of Nano-Scale Mechanics
4. Energy Methods and Variational Mechanics
5. Fundamentals of Bio-Mechanics: Trauma and Injury
6. Mechanics-of-Materials
7. Machine Design
8. Entrepreneurship, Strategic Management of Technology and Innovation
9. Risk-Management, Hedging,
10. Valuation of Technology Ventures

4.C Extension and Outreach Activities

Short-Courses Taught

1. AI Applications in Semiconductor Packaging, Lall, P., <https://ieeexplore.ieee.org/courses/details/EDP808>, Nov 12, 2025
2. Lall, P., Automotive Electronics Reliability – Assurance Approaches and Challenges, IEEE ESTC Conference, Berlin, Germany, September 11-14, 2024.
3. Professional Development Course: Additive Flexible Hybrid Electronics – Manufacturing and Reliability, Lall, P., IEEE Electronic Components and Technology Conference, Denver, CO, May 28-31, 2024.
4. Automotive Electronics Reliability – Assurance Challenges and Opportunities, Lall, P., IEEE EuroSIME Conference, Catania, Italy, April 7-10, 2024.
5. Automotive Electronics Reliability – Challenges and Opportunities, Lall, P., IEEE Electronic Packaging Technology Conference, Singapore, Dec 5-8, 2023.
6. Professional Development Course: Additive Flexible Hybrid Electronics – Manufacturing and Reliability, Lall, P., IEEE Electronic Components and Technology Conference, Orlando, FL, May 30-June 2, 2023.
7. Semiconductors in Automotive Technology Trends and Reliability, Lall, P., International Reliability Physics Symposium, Monterey, CA, March 26-30, 2023.
8. Semiconductors in Automotive Technology Trends and Reliability, Gupta, V., Lall, P., IMAPS Device Packaging Conference, March 13-16, 2023.
9. Professional Development Course: Additive Flexible Hybrid Electronics – Manufacturing and Reliability, Lall, P., IEEE Electronic Components and Technology Conference, San Diego, CA, May 31-June 3, 2022.
10. Lall, P., Featured Talk: Semiconductor Packaging Challenges For Automotive Applications, IThERM, San Diego, CA, May 31-June 4, 2022.
11. Lall, P., Gupta, V., Semiconductor Packaging Design Materials and Reliability for Automotive Applications, IMAPS Systems-in-Packaging Conference, June 20, 2022.
12. Lall, P., Additive Printed Flexible Electronics, Professional Development Course, IEEE ESTC, Sibiu, Romania, September 13, 2022.

13. Lall, P., DISTINGUISHED-LECTURE: Additively-Printed Multilayer Flexible Substrates with Z-axis Interconnects, IEEE Silicon Valley Area Chapter, March 18, 2021.
14. Flexible Hybrid Electronics – Manufacturing and Reliability, Pradeep Lall, Course-9, IEEE Electronics Components and Technology Conference, Virtual Conference, June 1- July 4, 2021
15. Flexible Hybrid Electronics – Manufacturing and Reliability, Pradeep Lall, Course-12, IEEE Electronics Components and Technology Conference, Las Vegas, Nevada, May 28, 2019
16. Flexible Hybrid Electronics – Manufacturing and Reliability, Pradeep Lall, Course-12, IEEE Electronics Components and Technology Conference, San Diego, California, May 29, 2018
17. Flexible Hybrid Electronics, Pradeep Lall, Course-13, IEEE Electronics Components and Technology Conference, Lake Buena Vista, Florida, May 30, 2017
18. Shock and Vibration Reliability of Electronics in Automotive and Aerospace Applications, Pradeep Lall, Professional Development Short Course, IEEE EuroSIME Conference, Budapest, Hungary, April 19, 2015.
19. Course T8: Shock Impact Reliability of Portable Electronics, Pradeep Lall, Professional Development Short Course, SMTAI Conference, Rosemont, Illinois, October 28, 2014.
20. Course S.A.4: Prognostics and Health Management of Electronics Systems, IEEE Prognostics Health Management Conference, Spokane, Washington, June 22, 2014.
21. Shock-Impact Reliability of Portable Electronics, Course 10, Pradeep Lall, IEEE Electronics and Components Conference (ECTC), Orlando, FL, May 27, 2014.
22. Prognostics and Health Monitoring of Electronic Systems in Shock, Vibration and Thermo-mechanical Environments, Pradeep Lall, Professional Development Short-Course, IEEE EuroSimE Conference, Linz, Austria, April 17, 2011
23. Failure Mode Classification for Prognostication of Electronic Systems, Pradeep Lall, Professional Development Short-Course, IEEE PHM Conference, Denver, Colorado, June 20, 2011
24. Resistance Spectroscopy Based Methods for Prognostication of Electronics, Pradeep Lall, Delivered via Adobe-Connect, March 26, 2010
25. Failure Mode Classification for Prognostication of Electronic Systems under Shock and Vibration, Pradeep Lall, Delivered via WEBEX, April 14, 2010
26. Interrogation of System State in Leadfree Electronics under Multiple Thermal Environments, Pradeep Lall, Delivered via WEBEX, October 15, 2010.
27. Hedging Risk in New Technology Ventures, Mechanical Engineering Alumni Conference, Lodge and Conference Center at Grand National, November 9-10, 2008.
28. Risk Management Strategies in New Technology Ventures, Mechanical Engineering Alumni Conference, Lodge and Conference Center at Grand National, November 4-5, 2007.
29. Product Development in Technology Markets, Mechanical Engineering Alumni Conference, Lodge and Conference Center at Grand National, October 7-8, 2005.
30. Strategies for Risk Management in Technology Markets, Mechanical Engineering Alumni Conference, Lodge and Conference Center at Grand National, Oct 1-2, 2004.
31. Lall, P., “High-Temperature Electronics,” NSF-CAVE Short Course, Duration: 4-hours, April 30, 2003.

Outreach Courses Taught

1. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2025.
2. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2024.
3. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2023.
4. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2022.
5. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2021.
6. Lall, P., MECH 7390/7396, Variational Mechanics, Fall 2020
7. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2020.
8. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2019.
9. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2018.
10. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2017.
11. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2016.
12. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2015.
13. Lall, P., MECH 7390/7396, Variational Mechanics, Fall 2014.
14. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2014.
15. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2013.

16. Lall, P., MECH 7320/7326, Continuum Mechanics and Tensor Analysis, Fall 2012.
17. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2012.
18. Lall, P., MECH 7390/7396, Variational Mechanics, Fall 2011.
19. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2011.
20. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2010.
21. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2009.
22. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2007.
23. Lall, P., MECH 6390/6396, Fundamentals of the Finite Element Method, Spring 2004.

Alumni Conferences

1. Transportation Electronics, Modeling, Materials, Performance and Reliability, Pradeep Lall, Auburn University Elements of Mechanical Engineering Conference, October 1 - 2, 2004.
2. Transportation Electronics, Modeling, Materials, Performance and Reliability, Pradeep Lall, Auburn University Elements of Mechanical Engineering Conference, October 9, 2003.

Mechanical Simulation-Tool Inventions

Conceptualized and Created Mechanical Simulation tool-sets including:

1. Reliability Forecasting System (Motorola, 1997) - a software tool set based on closed-form models for solder joint thermal fatigue reliability, which interfaces with Mentor Electrical Design.
2. Library of Primitives for System-level Modeling (Motorola, 1996) - a library of parametric nonlinear finite element models aimed at assessment of board-level reliability.
3. Computer-Aided Design for Microelectronic Packages, CADMP, (CALCE Center, 1992) tool set for design and reliability evaluation of microelectronic packages.

Panel Participant

1. Lall, P., Panelist in the Panel titled: Opportunities to work with Auburn Research Centers - Patriot Event Space, Auburn University Engineering Research Symposium on Advanced Manufacturing, Huntsville, AL, March 20, 2025.
2. Lall, P., PANELIST in WORKSHOP 4: Advancing Electronics Packaging and Heterogeneous Integration: Insights from InterPACK 2024 Panels, Tutorials and Workshops, ASME InterPACK, San Jose, CA, Oct 8-11, 2024
3. Lall, P., PANELIST, Additive Manufacturing For Domestic Electronics Packaging, Spoke on the topic of: "Promise of Additive Fabrication Processes for Heterogenous Integration Packaging", ASME InterPACK, San Jose, CA. pp. 1-10, October 8-10, 2024.
4. Lall, P. Panelist in the Panel titled: Model-based design of novel electronic components and systems – challenges and opportunities, Moderated by Przemek Gromala, IITHERM Conference, June 1- July 4, 2021
5. Lall, P., Panelist in panel titled - Packaging Challenges for Automotive Applications, SMTAI Conference, Moderated by Andrew Mawer, November 2, 2021.
6. Lall, P., Panelist: NASA's In-Space Manufacturing and the On-Demand Manufacturing of Electronics, CLB.PNL23, ASCEND Conference, November 15, 2021
7. Panelist, Sustainability and Power, FLEX Conference, Feb 22-26, 2021
8. Panel Session-Chair, Additive Printed Electronics, ASME InterPACK, October 28th, 2020
9. Panelist, Track-8 Panel: Reliability in the Age of AI: Opportunities and Challenges, ASME InterPACK, Los Angeles, CA, October 8, 2019
10. Panelist: Panel on challenges in Advanced Packaging for Harsh Environment Panel, Pradeep Lall, Presented at the ASME InterPACK Conference, August 28, 2018.
11. Material and Package Reliability Needs/Challenges for High Temp Industrial Environments, Vikas Gupta (Panel Co-Chair), Pradeep Lall (Panel Co-Chair), 2017 ECTC Special Session (Applied Reliability), Tuesday, 10:00–11:30 AM, May 30, 2017
12. Panel: PHM Research – Now Planned and Needed, Pradeep Lall, Presented at the *IEEE PHM Conference*, Denver, CO, June 20-23, 2011.
13. Panel on "Virtual Reliability Prediction and Linkage to Field Conditions with Applications to Microelectronics", ASME InterPACK Conference, San Francisco, July 17-23, 2005.

14. Panel on "Challenges in Modeling of Accelerated Life Testing", IThERM 9th Intersociety Conference on Thermal and Thermo-mechanical Phenomena, Las Vegas, Nevada, June 1-4, 2004.
15. Rule Based Design Knowledge Acquisition Definition Project the Aries Project, Core Team Member on "Council on Reliability, Quality and Competitiveness", The Aries Project, April, 1993- February, 1995.
16. Physics-of-Failure, Electronic Industries Association (EIA), G-41, R & M Committee, Spring Meeting, Washington D.C., June 8-9, 1993
17. MIL-STD-499, Meeting of the Society of Automotive Engineers, G-11 Committee, January 16, 1992
18. Integrating Thermal Analysis of Electronics with Design, ASME Winter Annual Meeting, Atlanta, GA, December 1-6, 1991.

4.D. Service

Course Coordinator

MECH 3230, Machine Design, Course Coordinator (2003-2007) Development of MECH 3230 Folder and Data for ABET Review.

University Committees

Engineering Tenure and Promotion Committee (2008-present) Mechanical
Engineering Personnel Committee (2008-present)

List of Journals that I have Reviewed Papers for

1. IEEE Transactions on Advanced Packaging
2. IEEE Transactions on Components & Packaging Technologies
3. IEEE Transactions on Electronic Packaging Manufacturing
4. IEEE Transactions on Reliability
5. ASME Journal of Electronic Packaging

Books Reviewed (prior to publication)

1. Electronic Packaging and Interconnection Handbook by Charles A. Harper (Editor), 3rd edition, McGraw-Hill Professional Publishing; ISBN: 0071347453, February 18, 2000,
2. Air Cooling Technology for Electronic Equipment, by Sung-Jin Kim (Editor), Sang Woo Lee (Editor), CRC Press, ISBN: 0849394473, April 1996

Present Journal Editorships

1. Associate Editor, IEEE Transactions on Components and Packaging Technologies, August 2003 to 2023.
2. Member, Editorial Advisory Board, SMTA Journal, 2007 to present.
3. PHM Special Section Associate Editor, IEEE Transactions on Reliability, 2011-present.

Past Journal Editorships

1. Guest Editor, ASME Journal of Electronic Packaging, 2003.
2. Member, Editorial Advisory Board, Microelectronics & Reliability, 1998 – 2002
3. Associate Editor, IEEE Transactions on Reliability, 1994-2000
4. Guest Editor, Microelectronics Reliability, Special Issue on Microelectronic Packaging, 1998
5. Associate Editor, ASME Journal of Electronic Packaging, 2004 to 2011.
6. Associate Editor, IEEE Transactions Component Packaging Manufacturing, 1997 to 2011
7. Editor of Special Issue on Prognostics and Health Management for IEEE Reliability Digest, February 2015.
8. Associate Editor, Microelectronics Reliability, 2018-2019.

Conference and Session Chairmanships

1. Board of Governors, IEEE Electronics Packaging Society (EPS), Jan 2026 - Dec 2028.
2. Technical Committee, SMTA Pan Pacific Strategic Electronics Symposium, 2026
3. Track Director, Additive Manufactured Electronics Track (AME), SMTAI, 2025 4. Track Chair, Track-6, Flexible Electronics, ASME InterPACK, 2025
5. Member, IEEE Reliability Society AdCom, 2024-2026.
6. Task Force Lead, SEMI Development of Reliability & Test Standard Task Force, SEMI, 2023- Present.
7. Conference General Chair, ASME InterPACK, San Jose, CA, Oct 8-10, 2024
8. Session Chair, Lall, P., Session-6: Batteries and More, Session Chair, SMTA Pan Pacific Strategic Electronics Symposium, Kona, Big Island, HI, USA, pp. 1-12, Jan 29-Feb 1, 2024.
9. Panelist, Lall, P., Sustainability, NextFlex Innovation Days, March 26-27, 2024
10. Session Chair, Lall, P., Fan, X., Session 30: Process and Hybrid Bonding Modeling and Characterization, Electronics Components and Technology Conference, Denver, CO, May 31, 2024.
11. Session-Chair, Lall, P., DTM3 – Reliability and Virtual Prototyping, IEEE ESTC Conference, Berlin, Germany, September 11-14, 2024.
12. Panelist, Lall, P., Reliability Validation and Standards, NextFlex Workshop on Hybrid Electronics for Defense Applications, Arlington, VA, Oct 1-3, 2024.
13. Session Chair, Lall, P., Plenary Talk – OUSD IBAS RESHAPE Project, ASME InterPACK, San Jose, CA, Oct 8-11, 2024
14. Session Chair, Lall, P., Plenary Talk: The Use of Additive Hybrid Electronics as a Key Element in the National Strategy for Advanced Packaging, ASME InterPACK, San Jose, CA, Oct 8-11, 2024
15. Session Chair, Lall, P., 06-02: Reliability and Repairability of Additive Electronics, ASME InterPACK, San Jose, CA, Oct 8-11, 2024
16. Session Chair, Lall, P., 06-05: FHE Applications & Processing, ASME InterPACK, San Jose, CA, Oct 8-11, 2024.
17. Session Chair, Lall, P., 06-06: Advanced Materials & Processes for Printed Electronics II, ASME InterPACK, San Jose, CA, Oct 8-11, 2024
18. Track Co-Chair, Lall, P., Flexible, Wearable and Printed Electronics, ASME InterPACK, San Jose, CA, Oct 8-11, 2024
19. Session Chair, Lall, P., AME1: Additive Electronics Applications, SMTAI Conference, Rosemont, IL, Oct 21-24, 2024.
20. Session Chair, Lall, P., APT1: Innovations in Wafer Level and Fan-Out Packaging, SMTAI Conference, Rosemont, IL, Oct 21-24, 2024.
21. Conference General Vice-Chair, ASME InterPACK, San Diego, CA, October 24-26, 2023.
22. Sponsorship Chair, ASME InterPACK, Garden Grove, CA, Oct 25-27, 2022
23. Board of Governors, IEEE Electronics Packaging Society (EPS), Jan-2022-Dec 2024.
24. Track Co-Chair, SMTAI, Advanced Packaging Technology Track, Minneapolis, MN, October 1-November 3, 2022
25. Session-Chair, Lall, P., Session II: Product Development Challenges, NextFlex Winter FHE Symposium, San Jose, CA, March 1-3, 2022
26. Session Chair, Lall, P., Session-12: Manufacturing and Assembly Process Modeling, IEEE ECTC, San Diego, CA, May 31-Jun 4, 2022.
27. Session Chair, Lall, P., Session-39: Interaction Presentations-3, IEEE ECTC, San Diego, CA, May 31-Jun 4, 2022.
28. Session Chair, Lall, P., Session II: Technology Innovation and Partnership Opportunities, NextFlex Innovation Days, San Jose, CA, August 2-3, 2022.
29. Session Chair, Lall, P., APT2 - High-Performance Packaging, SMTAI Conference, Minneapolis, MN, November 1, 2022.
30. Session-Chair, CPI and Thermal Management Analyses for Heterogeneous Integration, Pradeep Lall and Tieyu Zhang, IEEE Electronic Components and Technology Conference, June 1-July 4, 2021
31. Member, IEEE Artificial Intelligence Policy Committee, 2021-present.
32. Board of Governors, IEEE Electronics Packaging Society (EPS), Jan-2019-Dec 2021.
33. VP of Publications, IEEE Reliability Society, 2017-2018
34. Conference Vice-Chair, ASME InterPACK 2021
35. Academic Co-Lead, NextFlex Automotive Technical Working Group, 2021-Present.

36. Academic Co-Lead, NextFlex Asset Situational Awareness Technical Working Group, 2016-Present
37. Member, IEEE Artificial Intelligence Policy Committee, 2021-present.
38. Member, IEEE Electronic Packaging Society Fellows Evaluation Committee, 2021
39. Member, IEEE Reliability Society Fellows Evaluation Committee, 2021
40. Track Co-Chair, SMTAI, Advanced Packaging Technology Track, Rosemont, IL, September 28-October 3, 2020
41. Session Chair, Session 36: Multiphysics and AI-Enhanced Modeling Approaches, IEEE ECTC, May 29, 2020.
42. Track Chair, Mechanics Track, IEEE IThERM, July 21-23, 2020
43. Session Chair, Session M-5: Package and Interconnect Reliability I, IThERM, July 21-23, 2020
44. Session Chair, Session M-9: Reliability of Advanced Packaging, IThERM, July 21-23, 2020
45. Track Chair, Track 3: Flexible and Wearable Electronics, ASME INTERPACK, October 27-29, 2020.
46. Track Co-Chair, SMTA Harsh Environment Electronics Conference, Advanced Packaging Technology, Rosemont, IL, September 22-26, 2019
47. Session Chair, SMTA International Conference, Session APT6: Thermal, September 26, 2019
48. Session Co-organizer, Technical 4-3: Flexible Electronics Packaging and Assembly, ASME InterPACK, Los Angeles, CA, October 9, 2019
49. Track Co-Chair, IThERM Conference, Mechanics and Reliability Track, San Diego, CA, May 28-May 31, 2019
50. Session Chair, M-2: Emerging Technologies: Wearable, Flexible, Printed Electronics, IThERM Conference, Mechanics and Reliability Track, San Diego, CA, May 28-May 31, 2019
51. Session Chair, M-8: Reliability and PHM I, Flexible, Printed Electronics, IThERM Conference, Mechanics and Reliability Track, San Diego, CA, May 28-May 31, 2019
52. Session Chair, M-9: Reliability and PHM II, Flexible, Printed Electronics, IThERM Conference, Mechanics and Reliability Track, San Diego, CA, May 28-May 31, 2019
53. Session Chair, M-10: Response and Reliability at High Strain II, Flexible, Printed Electronics, IThERM Conference, Mechanics and Reliability Track, San Diego, CA, May 28-May 31, 2019
54. Session Chair, Session 18: Warpage and Material Performance, IEEE Electronic Components and Technology Conference, Las Vegas, NV, May 30, 2019
55. Track Co-Chair, Advanced Packaging Track (APT), SMTAI Conference, Rosemont, IL, 2018
56. Session Chair, APT2: Assembly and Reliability of Bottom Termination Components, SMTAI Conference, Rosemont, IL, Oct 14-18, 2018
57. Track Co-Chair, ASME InterPACK Conference, San Francisco, CA, 2018
58. Track Co-Chair, ASME InterPACK Conference, San Francisco, CA, 2017
59. General Chair, IEEE PHM Conference, Ottawa, Canada 2016.
60. General Chair, IEEE PHM Conference, Austin, TX, 2015.
61. Session Chair, HE2 - Thermal Solutions for Power Electronics, SMTAI Conference, Rosemont, IL, September 28-Oct 2, 2014
62. Session Co-Chair, AAT5 – BGA Solder Joint Reliability, SMTAI Conference, Rosemont, IL, September 28-Oct 2, 2014
63. Symposium Co-Organizer, Harsh Environments Symposium, SMTAI Conference, Rosemont, IL, September 28-Oct 2, 2014.
64. Session Chair, IEEE Prognostics Health Management Conference, Spokane, WA, Session: M..B.2 – Electronics PHM, June 22-25, 2014
65. Session Chair, IEEE Prognostics Health Management Conference, Spokane, WA, Session: M..B.3 – Electronics PHM, June 22-25, 2014
66. Session Chair, Session 28: System-Level Thermal & Mechanical Models II, IEEE ECTC Conference, Orlando, FL, May 30, 2014.
67. Session Chair, Session K2: Modeling and Simulation-1, IThERM Conference, Orlando, FL, May 29, 2014.
68. Chair, Congress Steering Committee Senate, ASME Congress IMECE, 2013-present.
69. Congress Steering Committee Chair, ASME Congress IMECE, San Diego, CA, 2013 70. Member, IEEE USA Government Relations Council, R & D Committee, 2013 – present.
71. Member, IEEE Reliability Society AdCom, 2010 – 2019.
72. Member, IEEE Reliability Society Fellows Selection Committee, 2013 – present.
73. IEEE Reliability Society Representative on Electric Vehicle for EV 2012, 2012-Present.
74. CSC Representative on the Board on Technical Knowledge Dissemination (BTKD), ASME International Mechanical Engineering Congress and Exposition (IMECE), San Diego, CA, 2012-2013.

75. CSC Representative on Technical Communities Operating Board (TCOB), ASME International Mechanical Engineering Congress and Exposition (IMECE), San Diego, CA, 2012-2013.
76. Member of the ASME Nominating Committee, Committee is responsible for reviewing packages and selecting the next ASME President, 2012-2014.
77. Symposium Organizer, Harsh Environments Symposium, SMTAI Conference, Ft. Worth, TX, October 13-17, 2013.
78. Session Chair, HE3: Power Electronics Packaging, SMTAI Conference, Ft. Worth, TX, October 13-17, 2013.
79. Session Organizer, Session 4-4 Multiphysics Modeling, ASME InterPACK Conference, Burlingame, CA, July 16-18, 2013
80. Session Organizer, Session 5-1 Wire Bonding, ASME InterPACK Conference, Burlingame, CA, July 16-18, 2013
81. Session Chair, S.1.11 PHM Research Part 2, IEEE Prognostics and Health Management Conference, Gaithersburg, Maryland, June 24-27, 2013.
82. IEEE Reliability Society Representative on Electric Vehicles, 2011-2012.
83. Congress Steering Committee Chair, ASME Congress IMECE, Houston, TX, 2012
84. Modeling and Simulation Representative, ECTC Planning Meeting, Dallas, Texas, November 1-2, 2012.
85. Tutorials Chair, IEEE International Conference on Prognostics and Health Management (PHM), Denver, CO, June 18-21, 2012.
86. Congress Steering Committee Chair-Elect, ASME Congress IMECE, Houston, TX, Nov 2011- May 2012
87. Member, Conference Program Committee, IEEE International Conference on Prognostics and Health Management (PHM), Denver, CO, June 18-21, 2012.
88. Session Chair, Session MT2: Mechanics of Mold Compounds, Resins and Laminates, San Diego, California, May 30-June 1, 2012.
89. Session Chair, Tutorial Session-1, IEEE PHM Conference, Denver, CO, June 18-21, 2012.
90. Session Chair, PHM Research Part-2, IEEE PHM Conference, Denver, CO, June 18-21, 2012.
91. Symposium Organizer, Harsh Environments Symposium, SMTAI Conference, Orlando, FL, October 14-18, 2012.
92. Session Chair, AAT1: Bend and Shock Reliability of BGAs and CSPs, SMTAI Conference, Orlando, FL, October 14-18, 2012.
93. CSC Representative on BTKD, American Society of Mechanical Engineers, 2011-2012
94. CSC Representative on TCOB, American Society of Mechanical Engineers, 2011-2012
95. Congress Steering Committee Vice-Chair, ASME Congress IMECE, 2011
96. Member, Congress Steering Committee, ASME International Mechanical Engineering Congress and Exposition (IMECE), 2011.
97. Modeling and Simulation Representative, ECTC Planning Meeting, Dallas, Texas, November 3-4, 2010.
98. Panel-Member, Electronic Vehicle Controls and Unintended Acceleration, Pradeep Lall, National Academies Panel, Columbus, OH, Jan 18-19, 2011
99. Panel-Member, Electronic Vehicle Controls and Unintended Acceleration, Pradeep Lall, National Academies Panel, Washington, DC, March 3-4, 2011
100. Panel-Member, Electronic Vehicle Controls and Unintended Acceleration, Pradeep Lall, Washington, DC, Jan 27-28, 2011
101. Panel-Member, Electronic Vehicle Controls and Unintended Acceleration, Pradeep Lall, National Academies Panel, Woods Hole, MA, June 11-14, 2011
102. Panel-Member, Electronic Vehicle Controls and Unintended Acceleration, Pradeep Lall, National Academies Panel, Woods Hole, MA, August 22-24, 2011
103. Tutorials Chair, IEEE International Conference on Prognostics and Health Management (PHM), Denver, CO, June 20-23, 2011.
104. Member, Conference Program Committee, IEEE International Conference on Prognostics and Health Management (PHM), Denver, CO, June 20-23, 2011.
105. Member, Technical Program Committee, SMTAI Conference, 2011 - Present.
106. IEEE Reliability Society Representative on Electric Vehicle for EV 2012, 2011-Present.
107. Session Chair, Session 3-1 Damage, Fatigue, and Fracture I, Track-3; Modeling and Simulation, ASME InterPACK Conference, Portland, Oregon, July 6-8, 2011.
108. Session Organizer, Session 5-4 Solders & Solder Joint Reliability, Track-5; Multi-Physics Based Reliability, ASME InterPACK Conference, Portland, Oregon, July 6-8, 2011.
109. Session Chair, Tutorial Session-2, IEEE PHM Conference, Denver, CO, June 20, 2011.

110. Session Chair, PHM Design Techniques and Algorithms-I, IEEE PHM Conference, Denver, CO, June 21, 2011.
111. Session Chair, PHM Design Techniques and Algorithms-II, IEEE PHM Conference, Denver, CO, June 21, 2011.
112. Session Chair, PHM Design Techniques and Algorithms-III, IEEE PHM Conference, Denver, CO, June 22, 2011.
113. Symposium Organizer, Harsh Environments Symposium, SMTAI Conference, Ft. Worth, TX, October 16-20, 2011.
114. Session Chair, HE2: Metallization and Connector Failure Mechanisms, SMTAI Conference, Ft. Worth, TX, October 16-20, 2011.
115. Session Organizer, Session 6-1-1 Symposium on Quality and Reliability of Electronic/Photonic Packaging, ASME International Mechanical Engineering Congress and Exposition (IMECE), Denver, CO, November 11-17, 2011.
116. Chair, Modeling and Simulation Sub-committee, Electronic Components and Technology Conference, 2010-2011.
117. Vice-Chair, Modeling and Simulation Sub-committee, Electronic Components and Technology Conference, 2009-2010.
118. General Chair, ASME Congress IMECE, Vancouver, Canada, Nov 14-Nov 18, 2010
119. Member, Congress Steering Committee, ASME International Mechanical Engineering Congress and Exposition (IMECE), 2010.
120. Track Co-Chair, Panels Discussions, ITherm, Las Vegas, June 2-5, 2010
121. Session Chair, MT-1: Modeling and Simulation I, ITherm, Las Vegas, June 2-5, 2010.
122. Session Chair, AAT5 Effect of PCB Surface Finish on Lead-Free Solder Joint Reliability, SMTAI, Orlando, Oct 24-28, 2010
123. Panel-Member, National Academies Panel on Electronic Vehicle Controls and Unintended Acceleration, Detroit, Michigan, August 2-3, 2010.
124. Panel-Member, National Academies Panel on Electronic Vehicle Controls and Unintended Acceleration, Detroit, Michigan, September 13-14, 2010.
125. CSC Representative, ASME TCOB, Newark, New Jersey, September 23-24, 2010.
126. Panel-Member, National Academies Panel on Electronic Vehicle Controls and Unintended Acceleration, Washington, D.C., October 10-13, 2010.
127. Modeling and Simulation Representative, ECTC Planning Meeting, Dallas, Texas, November 4-5, 2010.
128. Panel-Member, National Academies Panel on Electronic Vehicle Controls and Unintended Acceleration, Washington, D.C., December 6-7, 2010.
129. Member Technical Committee, IEEE EuroSIME International Conference, Bordeaux, France, April 26-28, 2010.
130. Congress Technical Chair, ASME International Mechanical Engineering Congress and Exposition (IMECE), Orlando, FL, Nov 13-19, 2009.
131. Session Chair, Automotive, Industrial, Harsh Environment Electronics Applications, Session TP1, International Symposium on Microelectronics, Nov 1-5, 2009.
132. Session Chair, MFX6: Via and Plated Thru Hole Reliability in Lead-Free Assembly, SMTAI Conference, San Diego, California, Oct 4-8, 2009
133. Session Co-Chair, AAT1: Advancements in Electronic Packaging, SMTAI Conference, San Diego, California, San Diego, California, Oct 4-8, 2009
134. Session Chair, Session-19: Electronic Packaging, 2009 SEM Annual Conference and Exposition on Experimental and Applied Mechanics, Albuquerque, New Mexico, June 1-4, 2009.
135. Modeling and Simulation Technical Committee Vice-Chair, June 2009- June 2010, Electronic Components and Technology Conference, San Diego, California, May 26-30, 2009.
136. Track-Chair, Reliability Track, ASME InterPACK Conference, San Francisco, CA, July 19-23, 2009.
137. Session-Chair, Session 10-3 Leadfree Solders – I, ASME InterPACK Conference, San Francisco, CA, July 19-23, 2009.
138. Session Co-Chair, Session 10-8 Packaging Reliability - II, ASME InterPACK Conference, San Francisco, CA, July 19-23, 2009.
139. Congress Technical Vice-Chair, ASME International Mechanical Engineering Congress and Exposition (IMECE), Boston, MA, Oct 31-Nov 6, 2008.
140. Member, ASME Congress Steering Committee, 2007 to present.
141. Session-Chair, Session 2.3, Mechanics Track – Session 2, Materials Characteristics and Construction Modeling,

- 11th Intersociety Conference On Thermal and Thermo-mechanical Phenomena in Electronic Systems, IITHERM, Orlando, Florida, May 28-31, 2008.
142. Track Chair, Emerging Technologies Track, ASME International Mechanical Engineering Congress and Exposition (IMECE), Boston, MA, Oct 31-Nov 6, 2008.
 143. Topic Co-Organizer, Topic 6-6 Symposium on Quality and Reliability of Electronic/Photonic Packaging – I, ASME International Mechanical Engineering Congress and Exposition (IMECE), Boston, MA, Oct 31-Nov 6, 2008.
 144. Session Co-Chair, Session 6-6-1 Quality and Reliability of Electronic/Photonic Packaging – I, ASME International Mechanical Engineering Congress and Exposition (IMECE), Boston, MA, Oct 31-Nov 6, 2008.
 145. Session-Chair, Session-5: Solder Reliability, P. Lall, EuroSIME: Thermal, Mechanical and Multi-physics Simulation and Experiments in Micro-Electronics and Micro-Systems, Freiburg, Germany, April 21-23, 2008.
 146. Symposium Co-Chair, 5-8 Symposium on Quality and Reliability of Electronic/Photonic Packaging – I, ASME International Mechanical Engineering Congress and Exposition (IMECE), Seattle, WA, Nov 11-15, 2007.
 147. Session Chair, 5-8-2: Quality and Reliability of Electronic/Photonic Packaging 2 - Area Array Packaging (Technical Session), ASME International Mechanical Engineering Congress and Exposition (IMECE), Seattle, WA, Nov 11-15, 2007.
 148. Session Co-Chair, 5-8-3: Quality and Reliability of Electronic/Photonic Packaging 3 - Analysis and Test Methods (Technical Session), ASME International Mechanical Engineering Congress and Exposition (IMECE), Seattle, WA, Nov 11-15, 2007.
 149. Session Chair, AAT3: Mechanical-Shock and Bend Reliability of Ball-Grid Array Packages, Surface Mount Technology Association International Conference (SMTAI), Orlando, Florida, October 7-11, 2007.
 150. Track-Chair, Modeling and Simulation Track, ASME InterPACK, Vancouver, Canada, July 8-12, 2007. Coorganized 8-Sessions.
 151. Session-Chair, Chip and Packaging Failure Mechanism Models, Modeling and Simulation Track, ASME InterPACK, Vancouver, Canada, July 8-12, 2007.
 152. Session Chair, Characterization of Electronics Package Stress and Materials, SEM Annual Conference and Exposition on Experimental and Applied Mechanics, Springfield, MA, June 4-6, 2007.
 153. Session Chair, Session 6: 3D Packaging, Cu Low K, 57th IEEE Electronic Components and Technology Conference, Reno, Nevada, May 29 – June 1, 2007.
 154. Topic Organizer, Quality and Reliability Symposium, ASME International Mechanical Engineering Congress and Exposition (IMECE), Chicago, Illinois, November 5 – 10, 2006.
 155. Session Chair, Modeling of Cu-low K, 3D Packaging, Lead Free Solders – I, at the 56th IEEE Electronic Components and Technology Conference, San Diego, CA, May 30 – June 2, 2006.
 156. Session Chair, Reliability III: Board and Product Level Reliability, at the ITherm 2006, 10th Intersociety Conference on Thermal and Thermo-mechanical Phenomena, San Diego, California, May 30-June 2, 2006.
 157. Session Chair, Simulation and Tests-II, IEEE-CPMT International Symposium and Exhibition on advanced Packaging Materials Processes, Properties and Interfaces, Atlanta, Georgia, March 15-17, 2006.
 158. Topic Chair, Mechanics, Quality and Reliability, ASME International Mechanical Engineering Congress and Exposition (IMECE), Orlando, FL, November 5 – 11, 2005.
 159. Track Co-Chair, Modeling and Simulation Track, ASME InterPACK Conference, San Francisco, July 17 – 22, 2005.
 160. Session Chair, Shock, Drop, and Vibration Reliability – I, Reliability Track, ASME InterPACK Conference, San Francisco, July 22, 2005.
 161. Session Co-Chair, Electrical Modeling and Characterization, Modeling and Simulation Track, ASME InterPACK Conference, San Francisco, July 21, 2005.
 162. Session Chair, Thermal and Mechanical Simulation – I, at the 55th IEEE Electronic Components and Technology Conference, Orlando, FL, Jun 1 – 3, 2005.
 163. Chair, Modeling and Simulation Technical Committee, IEEE Electronic Components and Technology Conference, 2004 – 2005.
 164. Session Chair, Lead-Free Solders-II, in the ASME International Mechanical Engineering Congress and Exposition (IMECE), Anaheim, CA, November 13 – 19, 2004.
 165. Session Chair, Harsh Environments – I: Drop Impact, in the ASME International Mechanical Engineering Congress and Exposition (IMECE), Anaheim, CA, November 13 – 19, 2004.
 166. Program Chair, Electronics and Photonics Packaging Division, ASME International Mechanical Engineering Congress and Exposition (IMECE), Anaheim, CA, November 13 – 19, 2004.

167. Session Chair, Thermal and Mechanical Performance for Harsh Environments, Surface Mount Technology Association Conference, Chicago, Illinois, Sept. 26 – 30, 2004
168. Co-Chair, Modeling and Simulation Technical Committee, IEEE Electronic Components and Technology Conference, 2003 – 2004.
169. Session Chair, Shock and Vibration Modeling, 54th IEEE Electronic Components and Technology Conference, Las Vegas, Nevada, June 1 - 4, 2004.
170. Program Co-Chair, Electronics and Photonics Packaging Division, ASME ASME International Mechanical Engineering Congress and Exposition (IMECE), 2003
171. Track-Chair, Reliability, ASME InterPACK Conference, July 6-11, 2003
172. Modeling and Simulation Committee Member, IEEE Electronic Components & Technology Conference, 1998 to present.
173. Modeling and Simulation-I, Session Chair, Electronic Components and Technology Conference, New Orleans, Louisiana, May 27-30, 2003
174. Drop Impact and Interface Failure Mechanisms, Session Chair, ASME InterPACK Conference, Maui, Hawaii, July 6-11, 2003
175. Lead-Free Solders, Session Co-Chair, ASME InterPACK Conference, Maui, Hawaii, July 6-11, 2003
176. Session Chair, Structural Mechanics Center-of-Excellence (SMCOE), Motorola HERMES Symposium.
177. Session Co-Chair, Structural Mechanics, Motorola HERMES Symposium.
178. Motorola HERMES Symposium, Session Chair for the "Thermal Design & Reliability " Session, 1999 to present.
179. Motorola Vibration Center-of-Excellence (VCOE), Session Co-Chair, Motorola Advanced Manufacturing Technology (AMT) Symposium, July 1998 to Present.
180. Thermal Design & Reliability, Session Chair, Motorola Advanced Manufacturing Technology (AMT) Symposium, July 1998 to Present.
181. Motorola Mechanics Center-of-Excellence (MCOE), Session Chair, Motorola Summer AMT Symposium, Schaumburg, IL, July 22, 1997.
182. Second International High Temperature Electronics Conference, Session Co-Chair, Charlotte, North Carolina, June 5-10, 1994.
183. ASME International Electronics Packaging Conference, Session Co-Chair with Werner Engelmaier, for session on "Reliability in Electronic Packaging", Binghamton, New York, Sept.29-Oct.2, 1993
184. Advanced Technology Workshop on "The Influence of Temperature On Microelectronic Device Failure Mechanisms", Conference-Chair, College Park, MD, August 25, 1992